

# Ultra Low Current Consumption 300mA CMOS Voltage Regulator

# **LR6232 Series**

#### ■ INTRODUCTION

The LR6232 series are a group of positive voltage regulators manufactured by CMOS technologies with ultra low consumption and low dropout voltage, which provide large output currents even when the difference of the input-output voltage is small. The LR6232 series can deliver 300mA output current and allow an input voltage as high as 8V. The series are very suitable for the battery-powered equipments, such as RF applications and other systems requiring a quiet voltage source.

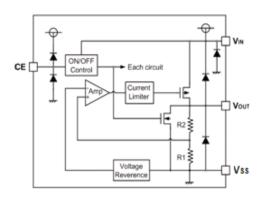
#### FEATURES

- Low Quiescent Current: 0.8µA
- Operating Voltage Range: 1.8V∼8V
- Output Current: 300mA
- Low Dropout Voltage: 110mV@100mA(V<sub>OUT</sub>=3.3V)
- Output Voltage: 1.0∼ 5.0V
- High Accuracy: ±2%/±1% (Typ.)
- High Power Supply Rejection Ratio: 50dB@1kHz
- Low Output Noise:
   27xV<sub>OUT</sub> μV<sub>RMS</sub> (10Hz~100kHz)
- Excellent Line and Load Transient Response
- Built-in Current Limiter, Short-Circuit Protection

#### APPLICATIONS

- Portable consumer equipments
- Radio control systems
- Laptop, Palmtops and PDAs
- Wireless Communication Equipments
- Portable Audio Video Equipments
- Ultra Low Power Microcontroller

#### **■ BLOCK DIAGRAM**



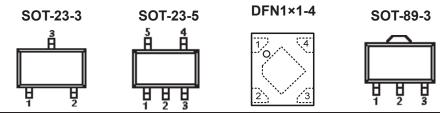
#### ORDER INFORMATION

LR623212345

DESIGNATOR	SYMBOL	DESCRIPTION
	Α	Standard
1	В	High Active, pull-down resistor built in, with C <sub>OUT</sub> discharge resistor
23	Integer	Output Voltage e.g.1.05V=②
	M/ MC/ MY	Package:SOT-23-3
	M	Package:SOT-23-5
( <del>4</del> )	P/PT/PL	Package:SOT-89-3
	F	Package:DFN1X1-4
(E)	-	2% Accuracy
(5)	1	1% Accuracy



# **■ PIN CONFIGURATION**



			PIN N	IUMBE	R	DIN		
SOT-23-3			SOT-89-3			PIN	FUNCTION	
M	MC	MY	Р	PT	PL	NAME		
1	3	3	1	2	2	V <sub>SS</sub>	Ground	
2	2	1	3	1	3	V <sub>OUT</sub>	Output	
3	1	2	2	3	1	V <sub>IN</sub>	Power input	

#### SOT-23-5

PIN NUMBER	SYMBOL	FUNCTION
1	V <sub>IN</sub>	Power Input Pin
2	V <sub>SS</sub>	Ground
3	CE	Chip Enable Pin
4	NC	No Connection
5	V <sub>OUT</sub>	Output Pin

# **DFN1X1-4**

PIN NUMBER F	SYMBOL	FUNCTION
1	V <sub>OUT</sub>	Output Pin
2	V <sub>SS</sub>	Ground
3	CE	Chip Enable Pin
4	V <sub>IN</sub>	Power Input Pin

# ■ ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

# (Unless otherwise specified, T<sub>A</sub>=25°C)

		•		, ,
PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage <sup>(2)</sup>	nput Voltage <sup>(2)</sup>		-0.3~9	V
Output Voltage <sup>(2)</sup>		V <sub>OUT</sub>	-0.3~V <sub>IN</sub> +0.3	V
Output Current	Output Current		600	mA
	SOT-23		0.4	W
Dower Dissinction	DFN1X1-4		0.4	W
Power Dissipation	SOT-89	- P <sub>D</sub>	0.6	W
Operating Junction Temperature Range		Tj	-40~125	°C
Storage Temperature		T <sub>stg</sub>	-40~125	°C
Lead Temperature(Solo	dering, 10 sec)	T <sub>solder</sub>	260	°C



#### Note:

- (1) Stresses beyond those listed under *absolute maximum ratings may* cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods my affect device reliability.
- (2) All voltages are with respect to network ground terminal.

# ■ RECOMMENDED OPERATING CONDITIONS

PARAMETER	MIN.	NOM.	MAX.	UNITS
Supply voltage at V <sub>IN</sub>	1.8		8	V
Operating junction temperature range, T <sub>j</sub>	-40		125	°C
Operating free air temperature range, T <sub>A</sub>	-40		85	°C

# ■ ELECTRICAL CHARACTERISTICS

LR6232 Series  $(V_{IN}=V_{OUT}+1V, C_{IN}=C_{OUT}=1\mu F, T_A=25 ^{\circ}C, unless otherwise specified)$ 

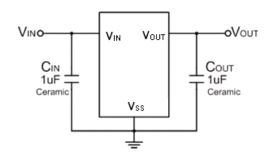
LR6232 Series	( • •						-	
PARAMETER	SYMBOL	C	ONDI.	TIONS	MIN.	TYP. <sup>(3)</sup>	MAX.	UNITS
Input Voltage	V <sub>IN</sub>			1.8	_	8	V	
Output Voltage Range	$V_{OUT}$				1.0	_	5	V
DC Output Accuracy			I <sub>OUT</sub> =	1 m A	-2	_	2	%
DC Output Accuracy			IOUT-	IIIIA	-1	_	1	%
Dropout Voltage	V <sub>dif</sub> <sup>(4)</sup>	I <sub>OUT</sub> =1	00mA	,V <sub>OUT</sub> =3.3V		110		mV
Supply Current		I <sub>OUT</sub>	1.2V≤	≤V <sub>OUT</sub> ≤3.3V	_	0.8	1.3	μA
Supply Current	I <sub>SS</sub>	=0	3.3V<	<v<sub>OUT≤5.0V</v<sub>		1.0	1.5	μA
Standby Current	I <sub>STBY</sub>		CE=	$V_{SS}$			0.1	μA
Line Regulation	$\Delta V_{ m OUT}$	I,	OUT =1	10mA		0.05	0.3	%/V
Line Regulation	$\overline{V_{OUT} \times \Delta V_{IN}}$	V <sub>OU</sub>	<sub>T</sub> +1V	SeV <sub>IN</sub> ≤8V		0.05	0.3	70/ V
Load Regulation	4)/	V <sub>IN</sub> = V <sub>OUT</sub> +1V,			10	_	mV	
Load Regulation	<u>∆</u> V <sub>OUT</sub>	1mA	∖≤l <sub>OUT</sub>	≤100mA		10		IIIV
Temperature	$\Delta V_{ m OUT}$	I	<sub>OUT</sub> =1	0mA,		100		nnm
Coefficient	$\overline{V_{OUT} \times \Delta T_A}$	-40°	°C <t<sub>A</t<sub>	<125°C		100		ppm
Output Current Limit	l	V <sub>OUT</sub> = (	$V_{OUT} = 0.5 \times V_{OUT(Normal)}$ ,		550	700	850	mA
Output Current Limit	I <sub>LIM</sub>	$V_{IN} = 5$	V		550	700	000	111/4
Short Current	I <sub>SHORT</sub>	,	V <sub>OUT</sub> :	=V <sub>SS</sub>	_	20	_	mA
				100Hz		70		
Power Supply	PSRR	I <sub>OUT</sub> =50	)m A	1kHz	_	50	_	dB
Rejection Ratio	FORK	100T-30		10kHz		40		ub
				100kHz		35		
Output Noise Voltage	V <sub>ON</sub>	BW=10Hz to 100kHz			27 x V <sub>OUT</sub>		$\mu V_{RMS}$	
CE "High" Voltage	V <sub>CE</sub> "H"				1.5		V <sub>IN</sub>	V
CE "Low" Voltage	V <sub>CE</sub> "L"						0.3	V
C <sub>OUT</sub> Auto-Discharge	Б	VII	<sub>N</sub> =5V,	V <sub>OUT</sub> =3.0V,		200		_
Resistance	R <sub>DISCHRG</sub>		V <sub>CE</sub> =	:V <sub>SS</sub>		200		Ω

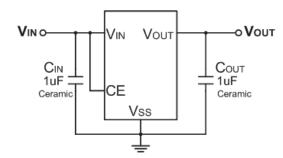


Note:

- (3) Typical numbers are at 25°C and represent the most likely norm.
- (4)  $V_{dif}$ : The Difference Of Output Voltage And Input Voltage When Input Voltage Is Decreased Gradually Till Output Voltage Equals To 98% Of  $V_{OUT}$  (E).

#### ■ TYPICAL APPLICATION CIRCUIT





#### APPLICATION INFORMATION

#### **Selection of Input/ Output Capacitors**

In general, all the capacitors need to be low leakage. Any leakage the capacitors have will reduce efficiency, increase the quiescent current.

A recent trend in the design of portable devices has been to use ceramic capacitors to filter DC-DC converter inputs. Ceramic capacitors are often chosen because of their small size, low equivalent series resistance (ESR) and high RMS current capability. Also, recently, designers have been looking to ceramic capacitors due to shortages of tantalum capacitors.

Unfortunately, using ceramic capacitors for input filtering can cause problems. Applying a voltage step to a ceramic capacitor causes a large current surge that stores energy in the inductances of the power leads. A large voltage spike is created when the stored energy is transferred from these inductances into the ceramic capacitor. These voltage spikes can easily be twice the amplitude of the input voltage step.

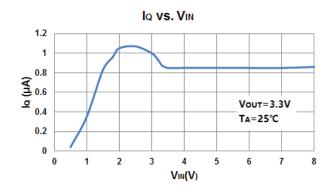
Many types of capacitors can be used for input bypassing, however, caution must be exercised when using multilayer ceramic capacitors (MLCC). Because of the self-resonant and high Q characteristics of some types of ceramic capacitors, high voltage transients can be generated under some start-up conditions, such as connecting the LDO input to a live power source. Adding a  $3\Omega$  resistor in series with an X5R ceramic capacitor will minimize start-up voltage transients.

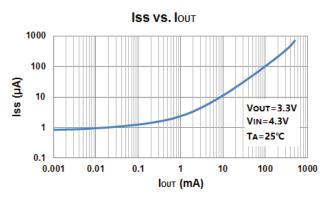
The LDO also requires an output capacitor for loop stability. Connect a  $1\mu F$  tantalum capacitor from OUT to GND close to the pins. For improved transient response, this output capacitor may be ceramic.

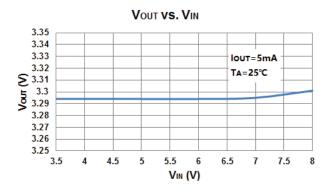


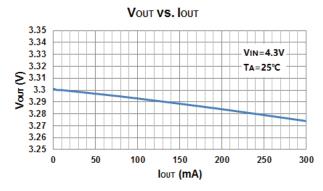
## ■ TYPICAL PERFORMANCE CHARACTERISTICS

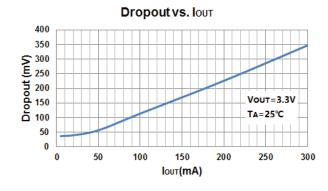
(V<sub>IN</sub>=V<sub>OUT</sub>+1V, C<sub>IN</sub>=C<sub>OUT</sub>=1μF, T<sub>A</sub>=25℃,unless otherwise specified)

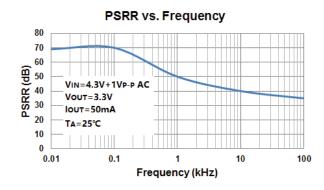


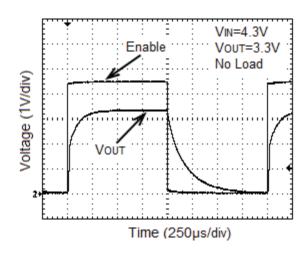


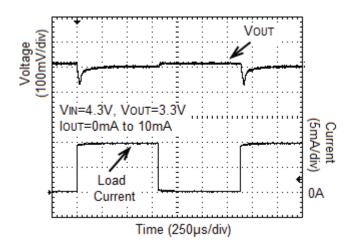








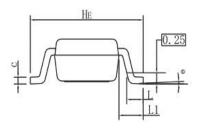


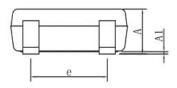


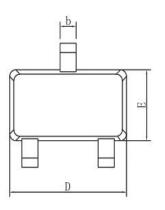


# PACKAGING INFORMATION

## • SOT-23-3 PACKAGE OUTLINE DIMENSIONS





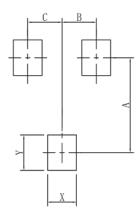


DIM	MIN	NOR	MAX
Α	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
С	0.10	0.17	0.20
D	2.80	2.90	3.00
E	1.50	1.60	1.70
е	1.80	1.90	2.00
L	0.20	0.40	0.60
L1	(	).60RE	F
HE	2.60	2.80	3.00
θ	0°	E E	10°
All [	Dimens	ions in	mm

## **GENERAL NOTES**

- 1.Top package surface finish Ra0.4±0.2um
- 2.Bottom package surface finish Ra0.7±0.2um
- 3.Side package surface finish Ra0.4±0.2um

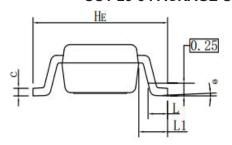
# **SOLDERING FOOTPRINT**

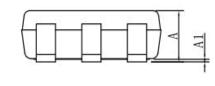


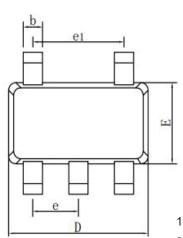
DIM	(mm)
X	0.80
Υ	0.90
Α	2.40
В	0.95
С	0.95



# • SOT-23-5 PACKAGE OUTLINE DIMENSIONS





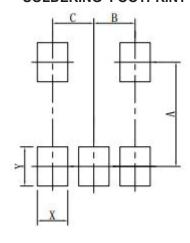


DIM	MIN	NOR	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
С	0.10	0.17	0.20
D	2.80	2.90	3.00
Е	1.50	1.60	1.70
е	0.85	0.95	1.05
e1	1.80	1.90	2.00
L	0.20	0.40	0.60
Ll	50	0. 60REI	F
HE	2.60	2.80	3.00
θ	00	a i	10°

## **GENERAL NOTES**

- 1.Top package surface finish Ra0.4±0.2um
- 2.Bottom package surface finish Ra0.7±0.2um
- 3.Side package surface finish Ra0.4±0.2um

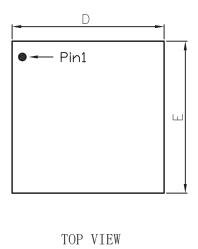
# **SOLDERING FOOTPRINT**

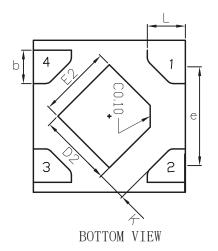


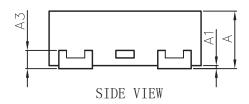
DIM	(mm)
X	0.70
Y	0.90
A	2.40
В	0.95
С	0.95



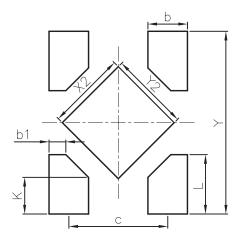
# DFNXX1-4 PACKAGE OUTLINE DIMENSIONS







Suggested Pad layout

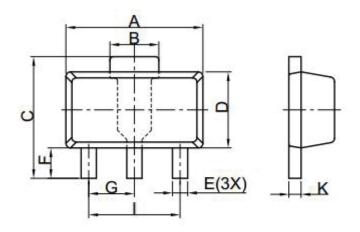


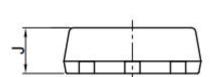
	DFN1010						
DIM	MIN	NOR	MAX				
A	0.34	0.37	0.40				
A1	0.01	0.02	0.05				
b	0.17	0.22	0.25				
L	0.20	0.25	0.30				
D	0.95	1.00	1.05				
Е	0.95	1.00	1.05				
D2	0.43	0.48	0.53				
E2	0.43	0.48	0.53				
е	e 0.65						
А3	0.127REF.						
K	0.15	-	-				
All	l Dimen	sions	in mm				

DFN1010							
DIM	(mm)						
X2	0.52						
Y2	0.52						
L	0.39						
Y	1.20						
K	0.24						
b	0.26						
С	0.65						
b1	0.11						



## • SOT-89-3 PACKAGE OUTLINE DIMENSIONS



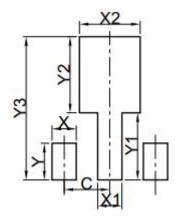


DIM	MIN	NOR	MAX		
Α	4.40	4.50	4.60		
В	1.40	1.60	1.80		
C	3.90	4.00	4.25		
D	5-C-2000	2.50	2.60		
E		0.50	0.58 1.20		
F	0.90	1.00			
G		1.50 BSC			
I S		3.00 BSC	ġ.		
J	1.40	1.50	1.60		
K	0.34	0.40	0.50		
	All Dime	nsions in r	nm		

#### **GENERAL NOTES**

- 1. Top package surface finish Ra0.4±0.2um
- 2. Bottom package surface finish Ra0.7±0.2um
- 3. Side package surface finish Ra0.4±0.2um
- 4. Protrusion or Gate Burrs shall not exceed 0.10mm per side.

#### **SOLDERING FOOTPRINT**



DIM	(mm)
X	0.80
Y	1.20
X1	0.80
Y1	2.20
X2	2.00
Y2	2.50
С	1.50
Y3	4.70



# ■ ORDER INFORMATION APPENDIX

Device <sup>(5)</sup>	Package	Output Voltage <sup>(6)</sup>	Marking (8)	Shipping
LR6232AxxM	SOT-23-3	1.0V~5.0V	4AX	3K/Reel
LR6232AxxMC	SOT-23-3	1.0V~5.0V	4CX	3K/Reel
LR6232AxxMY	SOT-23-3	1.0V~5.0V	4YX	3K/Reel
LR6232BxxM	SOT-23-5	1.0V~5.0V	4BX	3K/Reel
LR6232AxxP	SOT-89-3	1.0V~5.0V	4DX	1K/Reel
LR6232AxxPT	SOT-89-3	1.0V~5.0V	4TX	1K/Reel
LR6232AxxPL	SOT-89-3	1.0V~5.0V	4LX	1K/Reel
LR6232BxxF	DFN1X1-4	1.0V~5.0V	MX	10K/Reel

(8): "XX" represents output voltage, eg"18" express that the output voltage is 1.8V

(9) : Output voltage varies from 1.0V to 5.0V, 0.1V an interval

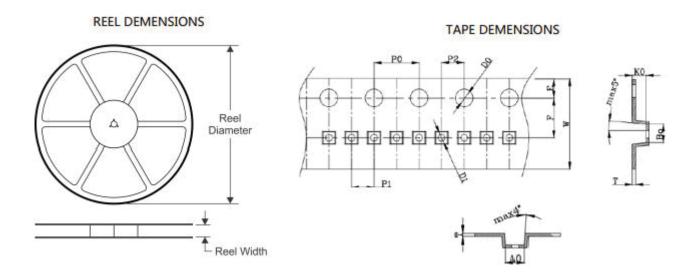
(10): The last letter "X" changes along with the output voltage, as figure below

(11): There are additional marking, which relates to the date code

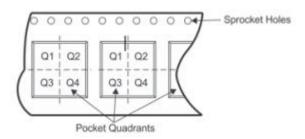
Voltage	 1.0	1.2	1.5	1.8	2.5	2.7	2.8	3.0	3.3	3.6	4.0	4.2	5.0	
Symble	 D	Е	F	G	Н	1	J	K	L	M	N	T	Р	



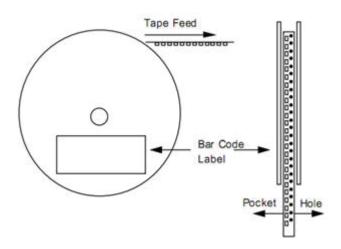
# **■ TAPE AND REEL INFORMATION**



## PIN ORIENTATION



# **ROLLING ORIENTATION**





Device	Package	Reel	Reel	P0	P1	Α0	В0	K0	w	PIN1
		Diameter (mm)	width (mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	
LR6232AxxM	SOT-23-3	178 <u>±</u> 1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	0.010.1	NA
				_	_	_		_	8.0±0.1	
LR6232AxxMC	SOT-23-3	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	8.0±0.1	NA
LR6232AxxMY	SOT-23-3	178 <u>+</u> 1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	8.0±0.1	NA
LR6232BxxM	SOT-23-5	178 <u>±</u> 1	9.6±1.2	4.00±0.1	4.00±0.1	3.25±0.05	3.15±0.05	1.5±0.05	8.0±0.1	Q3
LR6232AxxP	SOT-89-3	178±1	13. $0^{+1}_{-0.5}$	4.00±0.1	8.00±0.1	4.75±0.1	4.2±0.1	1.75±0.1	12. $0^{+0.3}_{-0.1}$	NA
LR6232AxxPT	SOT-89-3	178±1	13. $0^{+1}_{-0.5}$	4.00±0.1	8.00±0.1	4.75±0.1	4.2±0.1	1.75±0.1	12. $0^{+0.3}_{-0.1}$	NA
LR6232AxxPL	SOT-89-3	178±1	13. $0^{+1}_{-0.5}$	4.00±0.1	8.00±0.1	4.75±0.1	4.2±0.1	1.75±0.1	12. 0 <sup>+0. 3</sup> <sub>-0. 1</sub>	NA
LR6232BxxF	DFN1X1-4	178 <u>±</u> 1	9.6±1.2	4.00±0.1	2.00±0.05	1.16±0.05	1.16±0.05	0.5±0.05	8.0±0.1	Q3

# 单击下面可查看定价,库存,交付和生命周期等信息

# >>LRC(乐山无线电)